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Serial No.: 09/832,884

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Applicant: Steve M. Danziger, et al.

Art Unit: 2829

Filed: April 12, 2001

Examiner: Evan T. Pert

Docket No: L/M-102-DIV

Customer No: 28892

For: Method and Apparatus for Evaluating a Known Good Die Using  
Both Wire Bond and Flip-Chip Interconnects

**AMENDMENT**

US Patent & Trademark Office  
2011 South Clark Place  
Customer Window, Mail Stop: **NON-FEE AMENDMENT**  
Crystal Plaza Two, Lobby, Room 1B03  
Arlington, VA 22202

Sir:

This amendment is response to the Office Action dated September 10, 2003. Claims 1 - 8 are pending in this application and have been rejected. Please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 5 of this paper.

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